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#### General Information

Series	KONNEKT Comm COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	1.3 g
Chip Size	2220-4
Shelf Life	78 Weeks
MSL	1

#### Specifications

Capacitance	4,000 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 PPM/C
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

#### Dimensions

L	5.7mm +/-0.4mm
W	10.3mm +/-0.8mm
T	10.3mm +/-0.8mm
B	0.6mm +/-0.35mm

#### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	125

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